

MOSFETs Silicon N-Channel MOS

# SSM3K35CTC

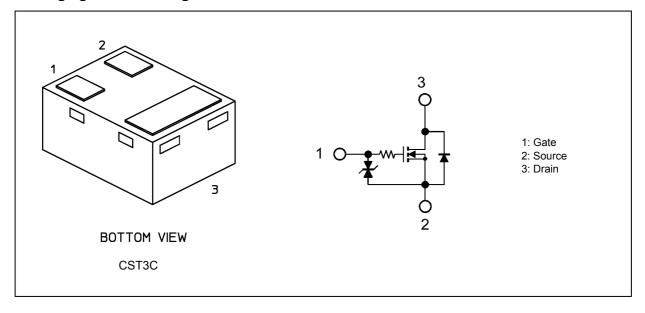
### 1. Applications

- High-Speed Switching
- Analog Switches

### 2. Features

- (1) 1.2-V gate drive voltage.
- (2) Low drain-source on-resistance
  - $\cdot$  R<sub>DS(ON)</sub> = 9.0  $\Omega$  (max) (@V<sub>GS</sub> = 1.2 V, I<sub>D</sub> = 10 mA)
  - $\cdot$  R<sub>DS(ON)</sub> = 3.1  $\Omega$  (max) (@V<sub>GS</sub> = 1.5 V, I<sub>D</sub> = 20 mA)
  - $\cdot$  R<sub>DS(ON)</sub> = 2.4  $\Omega$  (max) (@V<sub>GS</sub> = 1.8 V, I<sub>D</sub> = 150 mA)
  - $\cdot$  R<sub>DS(ON)</sub> = 1.6  $\Omega$  (max) (@V<sub>GS</sub> = 2.5 V, I<sub>D</sub> = 150 mA)
  - $\cdot$  R<sub>DS(ON)</sub> = 1.1  $\Omega$  (max) (@V<sub>GS</sub> = 4.5 V, I<sub>D</sub> = 150 mA)

### 3. Packaging and Pin Assignment





### 4. Absolute Maximum Ratings (Note) (Unless otherwise specified, T<sub>a</sub> = 25 °C)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		$V_{DSS}$	20	V
Gate-source voltage		$V_{GSS}$	±10	
Drain current	(Note 1)	I <sub>D</sub>	250	mA
Drain current (pulsed)	(Note 1)	I <sub>DP</sub>	600	
Power dissipation	(Note 2)	P <sub>D</sub>	500	mW
Channel temperature		T <sub>ch</sub>	150	°C
Storage temperature		T <sub>stg</sub>	-55 to 150	ç

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Ensure that the channel temperature does not exceed 150 °C.

Note 2: Device mounted on an FR4 board. (25.4 mm × 25.4 mm × 1.6 mm ,Cu pad: 645 mm<sup>2</sup>)

Note: The MOSFETs in this device are sensitive to electrostatic discharge. When handling this device, the worktables, operators, soldering irons and other objects should be protected against anti-static discharge.

Note: The channel-to-ambient thermal resistance,  $R_{th(ch-a)}$ , and the drain power dissipation,  $P_D$ , vary according to the board material, board area, board thickness and pad area. When using this device, be sure to take heat dissipation fully into account.



#### 5. Electrical Characteristics

### 5.1. Static Characteristics (Unless otherwise specified, T<sub>a</sub> = 25 °C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±1	μА
Drain cut-off current		I <sub>DSS</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V	_	_	1	
Drain-source breakdown voltage		V <sub>(BR)DSS</sub>	I <sub>D</sub> = 1 mA, V <sub>GS</sub> = 0 V	20	_	_	V
Gate threshold voltage	(Note 1)	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 100 μA	0.35	_	1.0	V
Drain-source on-resistance	(Note 2)	R <sub>DS(ON)</sub>	I <sub>D</sub> = 150 mA, V <sub>GS</sub> = 4.5 V	_	0.75	1.1	Ω
		R <sub>DS(ON)</sub>	I <sub>D</sub> = 150 mA, V <sub>GS</sub> = 2.5 V	_	1.1	1.6	
		R <sub>DS(ON)</sub>	I <sub>D</sub> = 150 mA, V <sub>GS</sub> = 1.8 V	_	1.4	2.4	
		R <sub>DS(ON)</sub>	$I_D = 20 \text{ mA}, V_{GS} = 1.5 \text{ V}$	_	1.7	3.1	
		R <sub>DS(ON)</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 1.2 V	_	2.4	9.0	
		R <sub>DS(ON)</sub>	$I_D$ = 150 mA, $V_{GS}$ = 4.5 V, $T_j$ = 125 °C	_	1.25	2.5	
Forward transfer admittance	(Note 2)	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 150 mA	_	0.5		S
Reverse drain current (pulsed)	(Note 2)	I <sub>DRP</sub>	_	_	_	600	mA

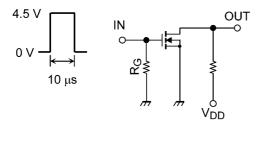
Note 1: Let  $V_{th}$  be the voltage applied between gate and source that causes the drain current ( $I_D$ ) to below (100  $\mu$ A for this device). Then, for normal switching operation,  $V_{GS(ON)}$  must be higher than  $V_{th}$ , and  $V_{GS(OFF)}$  must be lower than  $V_{th}$ . This relationship can be expressed as:  $V_{GS(OFF)} < V_{th} < V_{GS(ON)}$ . Take this into consideration when using the device.

Note 2: Pulse measurement.

## 5.2. Dynamic Characteristics (Unless otherwise specified, $T_a = 25$ °C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V,	_	18	36	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1 MHz	_	5	10	
Output capacitance	Coss			6	12	
Switching time (turn-on delay time)	t <sub>d(on)</sub>	V <sub>DD</sub> = 10 V, I <sub>D</sub> = 75 mA,	_	2	_	ns
Switching time (rise time)	t <sub>r</sub>	$V_{GS}$ = 0 to 4.5 V, $R_G$ = 10 $\Omega$	_	2	_	
Switching time (turn-off delay time)	t <sub>d(off)</sub>	]	_	6.5	_	
Switching time (fall time)	t <sub>f</sub>		_	5.5	_	

### 5.3. Switching Time Test Circuit





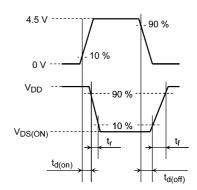


Fig. 5.3.2 Input Waveform/Output Waveform



## 5.4. Gate Charge Characteristics (Unless otherwise specified, $T_a = 25$ °C)

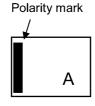
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD}$ = 10 V, $I_{D}$ = 200 mA,	_	0.34	_	nC
Gate-source charge 1	Q <sub>gs1</sub>	V <sub>GS</sub> = 4.5 V	_	0.09		
Gate-drain charge	Q <sub>gd</sub>		_	0.16		

### 5.5. Source-Drain Characteristics (Unless otherwise specified, T<sub>a</sub> = 25 °C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Diode forward voltage (N	ote 1)	$V_{DSF}$	$I_D = -150 \text{ mA}, V_{GS} = 0 \text{ V}$	_	-0.8	-1.2	V

Note 1: Pulse measurement.

### 6. Marking





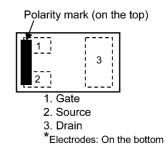


Fig. 6.2 Pin Condition (top view)



### 7. Characteristics Curves (Note)

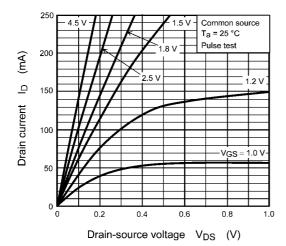


Fig. 7.1 I<sub>D</sub> - V<sub>DS</sub>

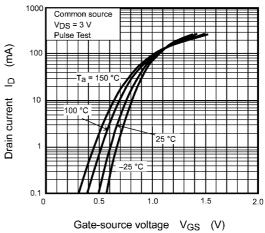


Fig. 7.2 I<sub>D</sub> - V<sub>GS</sub>

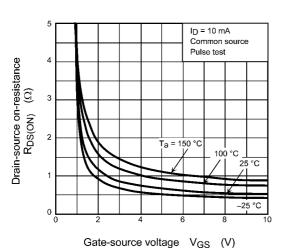


Fig. 7.3 R<sub>DS(ON)</sub> - V<sub>GS</sub>

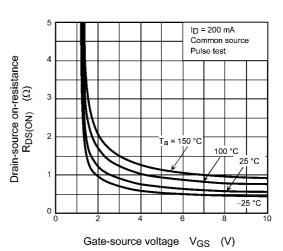


Fig. 7.4 R<sub>DS(ON)</sub> - V<sub>GS</sub>

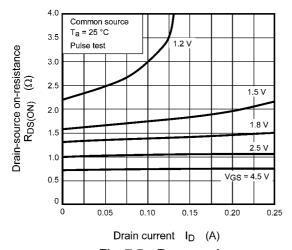


Fig. 7.5 R<sub>DS(ON)</sub> - I<sub>D</sub>

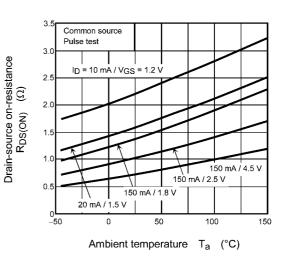
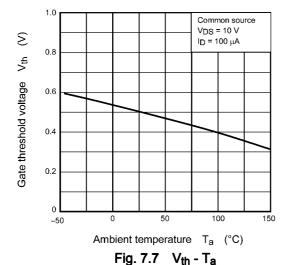
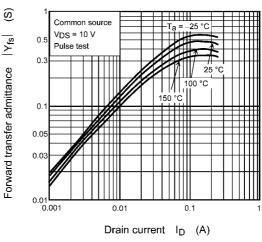


Fig. 7.6  $R_{DS(ON)}$  -  $T_a$ 









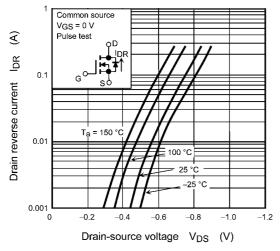


Fig. 7.9 I<sub>DR</sub> - V<sub>DS</sub>

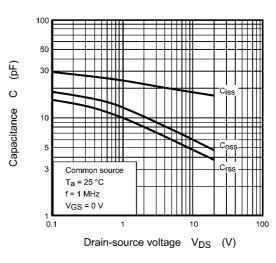
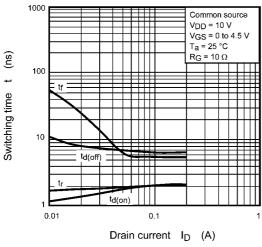


Fig. 7.10 C - V<sub>DS</sub>





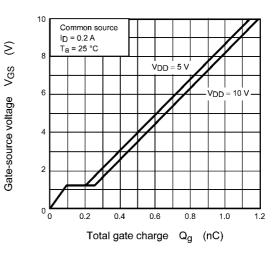
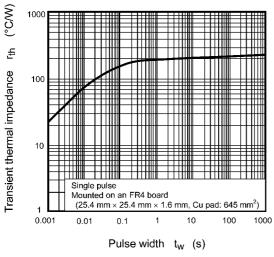


Fig. 7.12 Dynamic Input Characteristics

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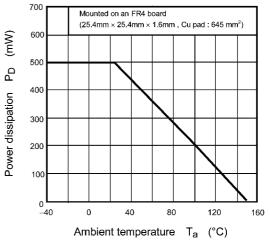


Fig. 7.13 rth - tw

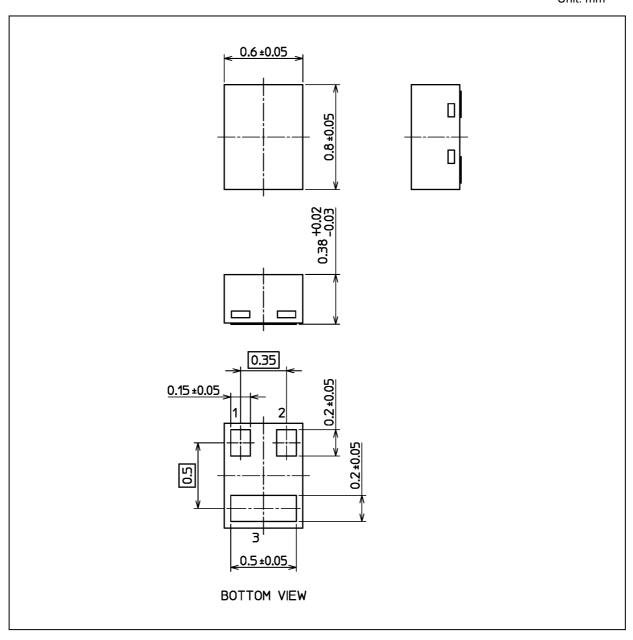
Fig. 7.14 P<sub>D</sub> - T<sub>a</sub>

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



### **Package Dimensions**

Unit: mm



Weight: 0.55 mg (typ.)

	Package Name(s)	
Nickname: CST3C		



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